

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	50	V
Collector-base voltage	$V_{CBO}$	50	
Input forward voltage	$V_{i(fwd)}$	40	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	$I_C$	100	mA
Total power dissipation- BCR183, $T_S \leq 102^\circ\text{C}$ BCR183S, $T_S \leq 115^\circ\text{C}$ BCR183U, $T_S \leq 118^\circ\text{C}$ BCR183W, $T_S \leq 124^\circ\text{C}$	$P_{tot}$	200 250 250 250	mW
Junction temperature	$T_j$	150	
Storage temperature	$T_{stg}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup> BCR183 BCR183S BCR183U BCR183W	$R_{thJS}$	$\leq 240$ $\leq 140$ $\leq 133$ $\leq 105$	K/W

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

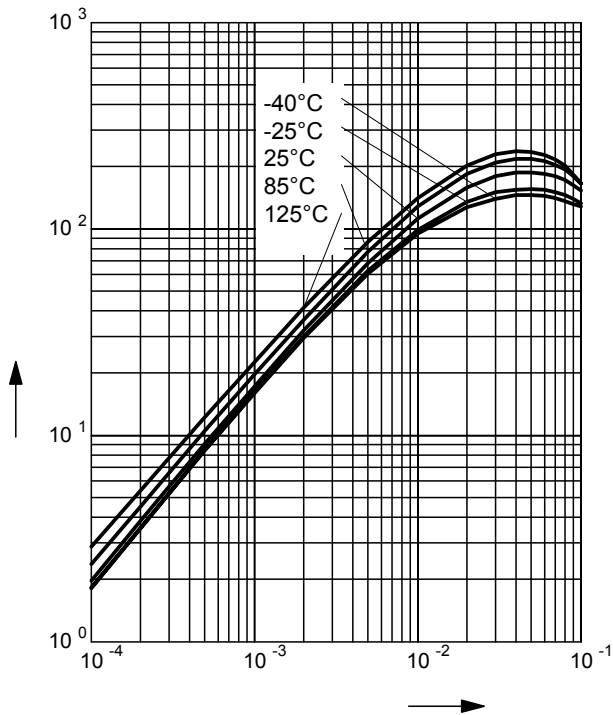
**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100\ \mu\text{A}$ , $I_B = 0$	$V_{(\text{BR})\text{CEO}}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10\ \mu\text{A}$ , $I_E = 0$	$V_{(\text{BR})\text{CBO}}$	50	-	-	
Collector-base cutoff current $V_{\text{CB}} = 40\ \text{V}$ , $I_E = 0$	$I_{\text{CBO}}$	-	-	100	nA
Emitter-base cutoff current $V_{\text{EB}} = 10\ \text{V}$ , $I_C = 0$	$I_{\text{EBO}}$	-	-	0.75	mA
DC current gain <sup>1)</sup> $I_C = 5\ \text{mA}$ , $V_{\text{CE}} = 5\ \text{V}$	$h_{\text{FE}}$	30	-	-	-
Collector-emitter saturation voltage <sup>1)</sup> $I_C = 10\ \text{mA}$ , $I_B = 0.5\ \text{mA}$	$V_{\text{CEsat}}$	-	-	0.3	V
Input off voltage $I_C = 100\ \mu\text{A}$ , $V_{\text{CE}} = 5\ \text{V}$	$V_{\text{i(off)}}$	0.8	-	1.8	
Input on voltage $I_C = 2\ \text{mA}$ , $V_{\text{CE}} = 0.3\ \text{V}$	$V_{\text{i(on)}}$	1	-	2.5	
Input resistor	$R_1$	7	10	13	kΩ
Resistor ratio	$R_1/R_2$	0.9	1	1.1	-
AC Characteristics					
Transition frequency $I_C = 10\ \text{mA}$ , $V_{\text{CE}} = 5\ \text{V}$ , $f = 100\ \text{MHz}$	$f_{\text{T}}$	-	200	-	MHz
Collector-base capacitance $V_{\text{CB}} = 10\ \text{V}$ , $f = 1\ \text{MHz}$	$C_{\text{cb}}$	-	3	-	pF

<sup>1)</sup>Pulse test:  $t < 300\ \mu\text{s}$ ;  $D < 2\%$

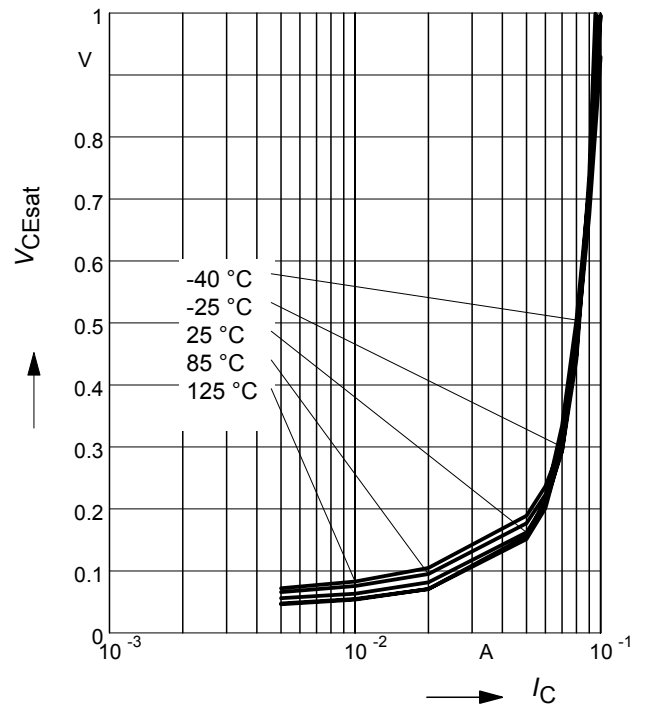
**DC current gain  $h_{FE} = f(I_C)$**

$V_{CE} = 5 \text{ V}$  (common emitter configuration)



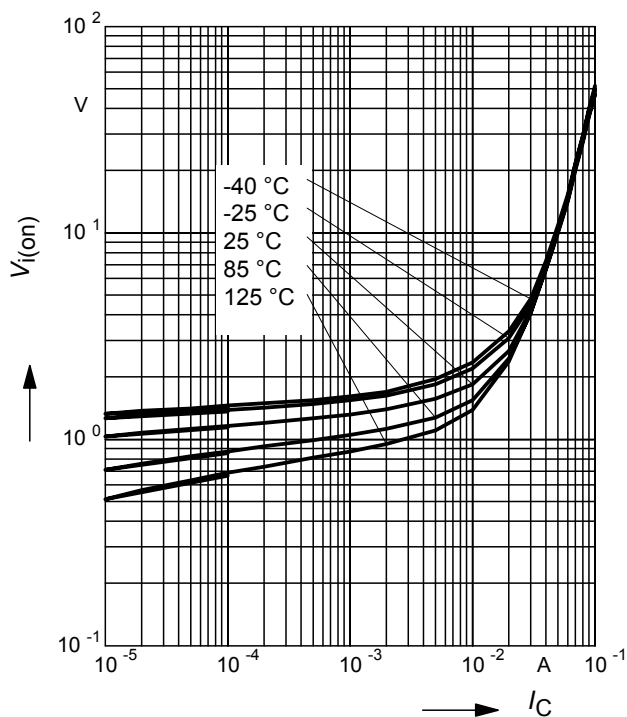
**Collector-emitter saturation voltage**

$V_{CEsat} = f(I_C)$ ,  $I_C/I_B = 20$



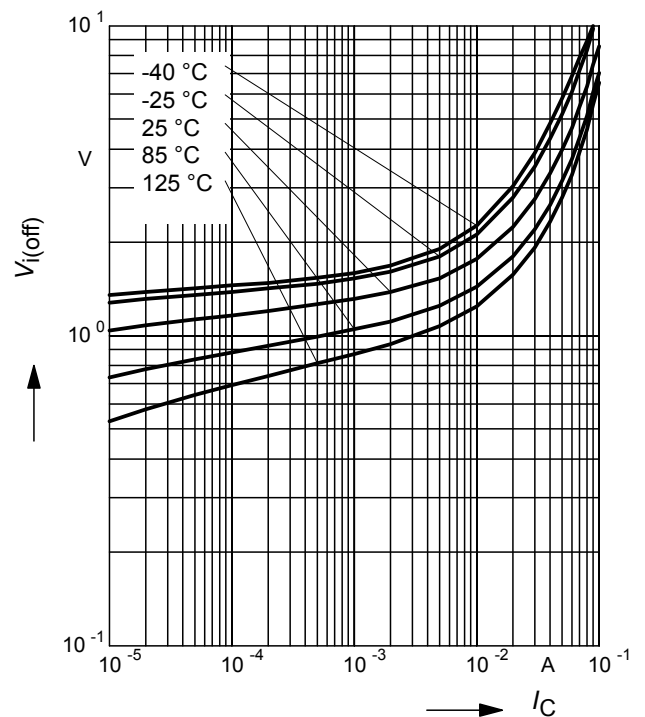
**Input on Voltage  $V_{i(on)} = f(I_C)$**

$V_{CE} = 0.3 \text{ V}$  (common emitter configuration)



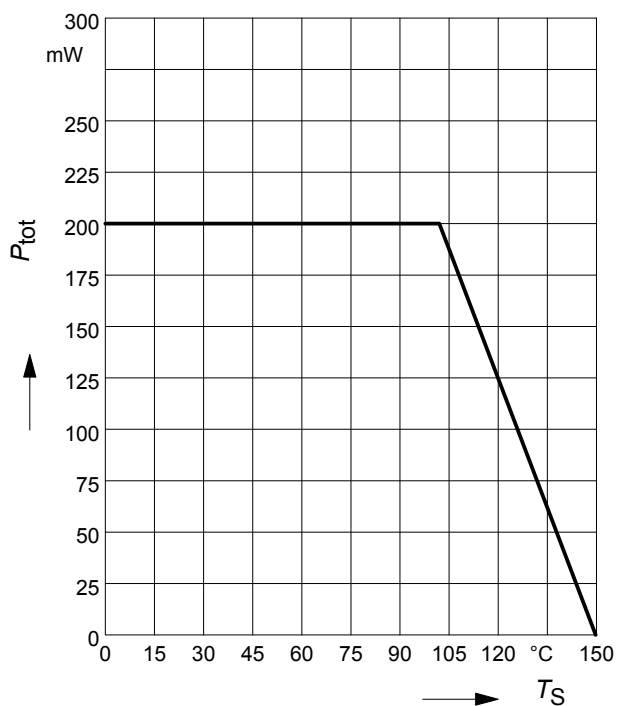
**Input off voltage  $V_{i(off)} = f(I_C)$**

$V_{CE} = 5 \text{ V}$  (common emitter configuration)



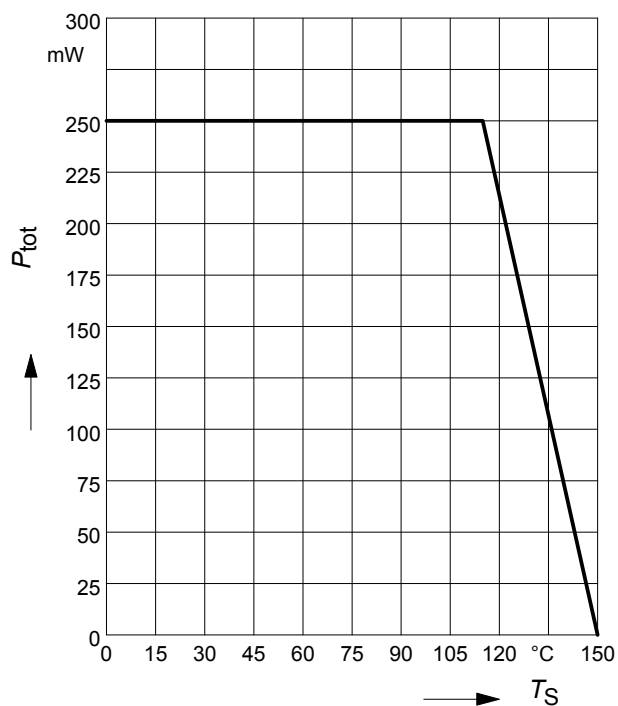
**Total power dissipation  $P_{\text{tot}} = f(T_S)$**

BCR183



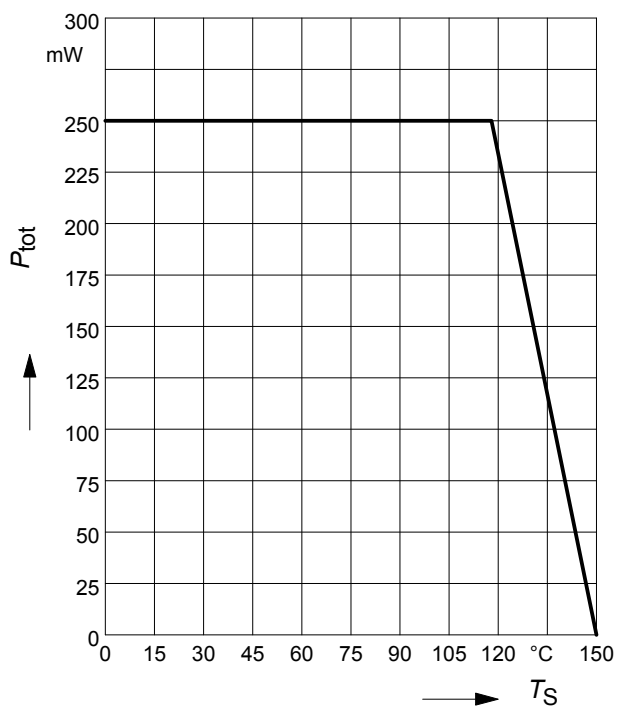
**Total power dissipation  $P_{\text{tot}} = f(T_S)$**

BCR183S



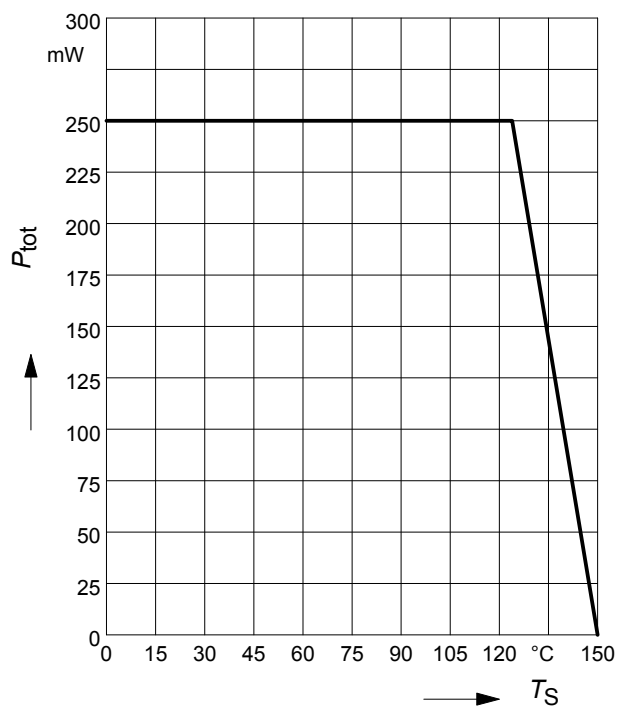
**Total power dissipation  $P_{\text{tot}} = f(T_S)$**

BCR183U



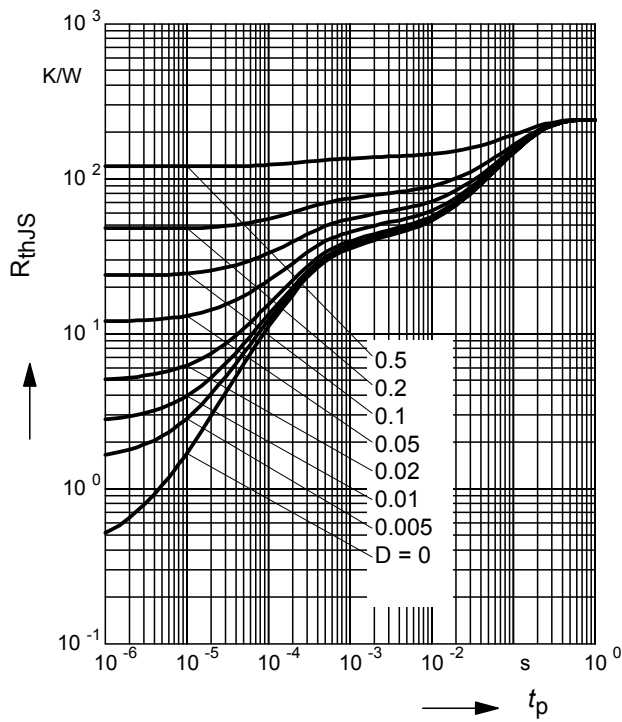
**Total power dissipation  $P_{\text{tot}} = f(T_S)$**

BCR183W



### Permissible Pulse Load $R_{thJS} = f(t_p)$

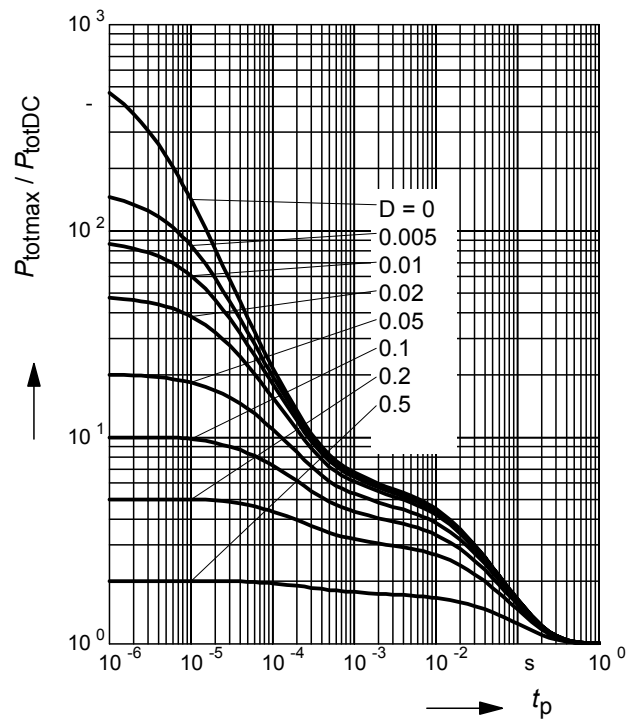
BCR183



### Permissible Pulse Load

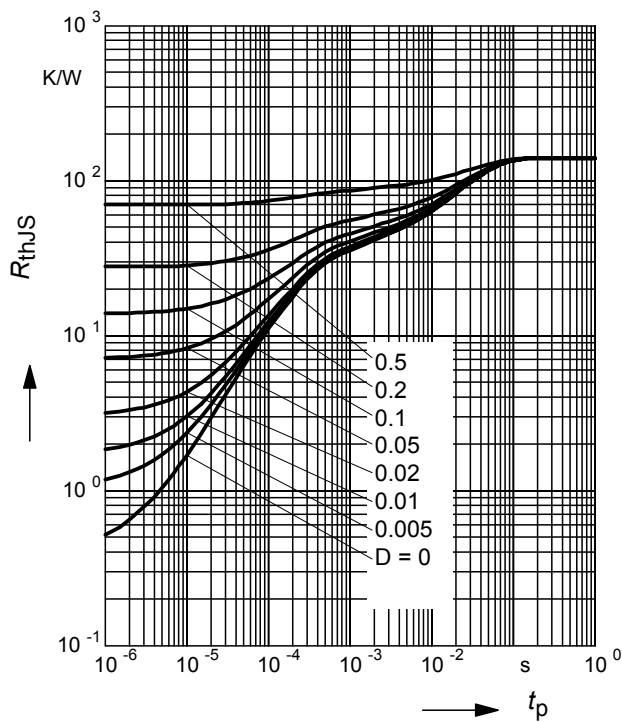
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR183



### Permissible Puls Load $R_{thJS} = f(t_p)$

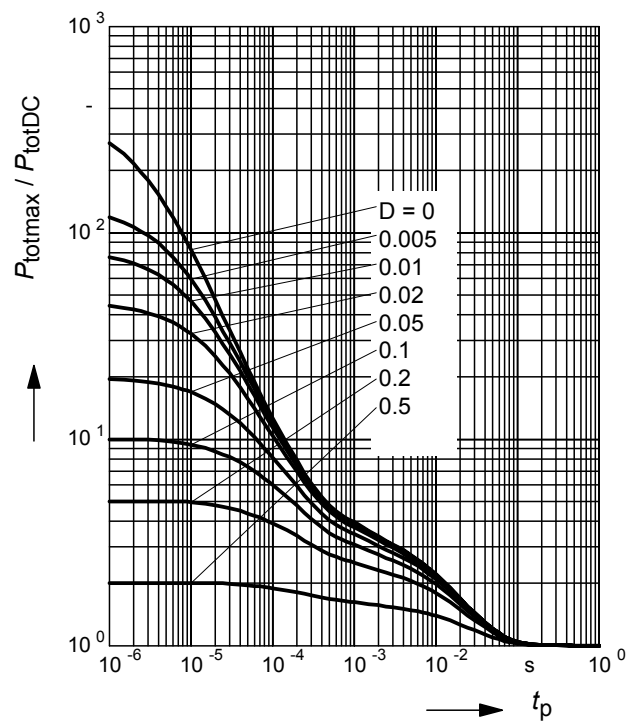
BCR183S



### Permissible Pulse Load

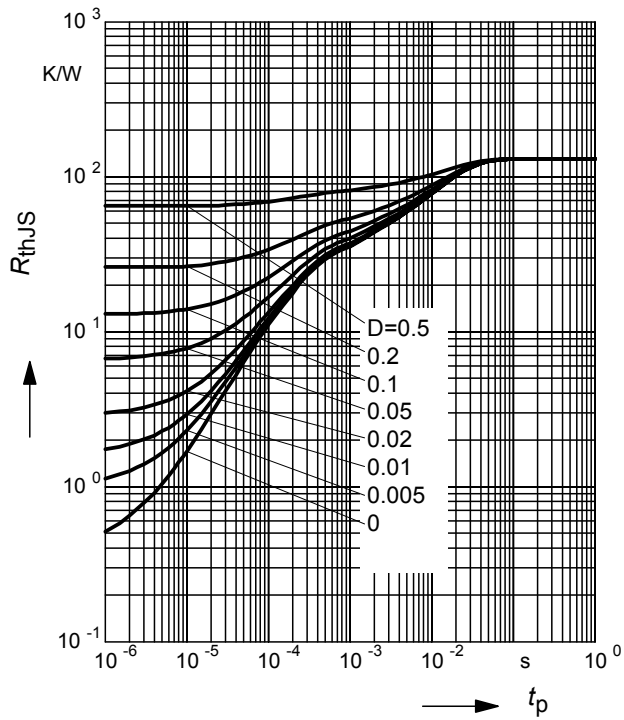
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR183S



### Permissible Puls Load $R_{thJS} = f(t_p)$

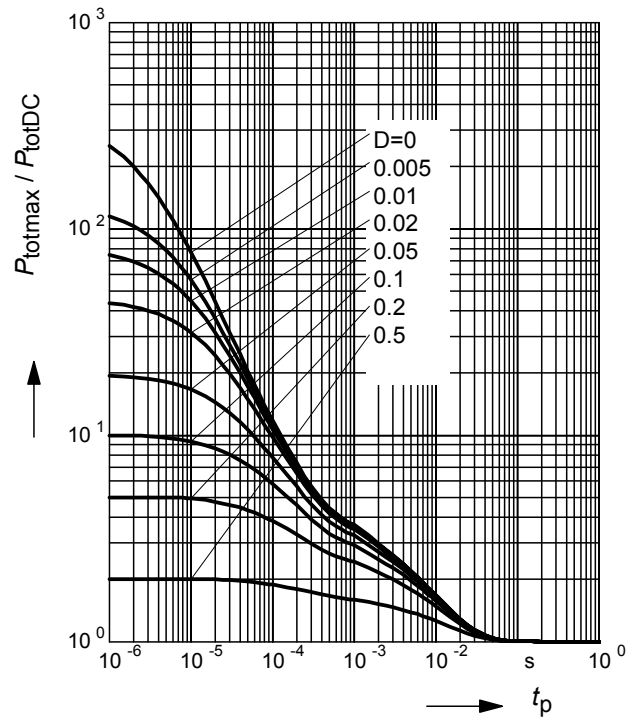
BCR183U



### Permissible Pulse Load

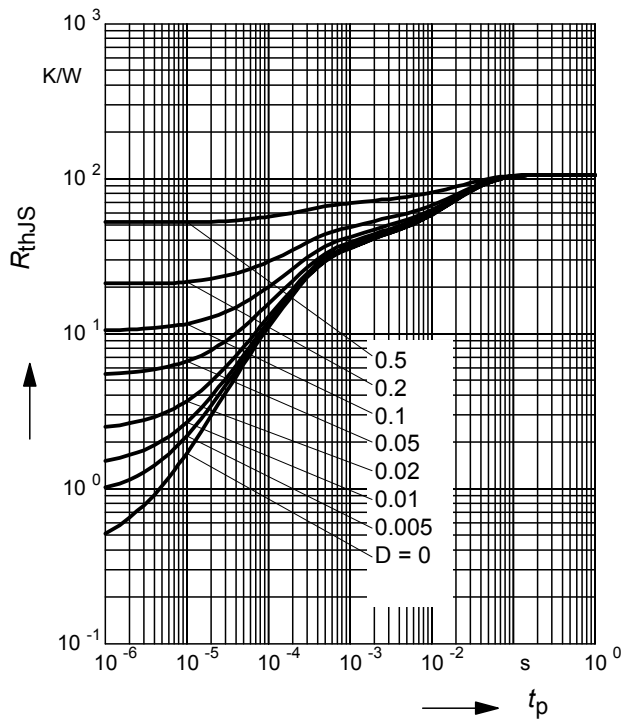
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR183U



### Permissible Puls Load $R_{thJS} = f(t_p)$

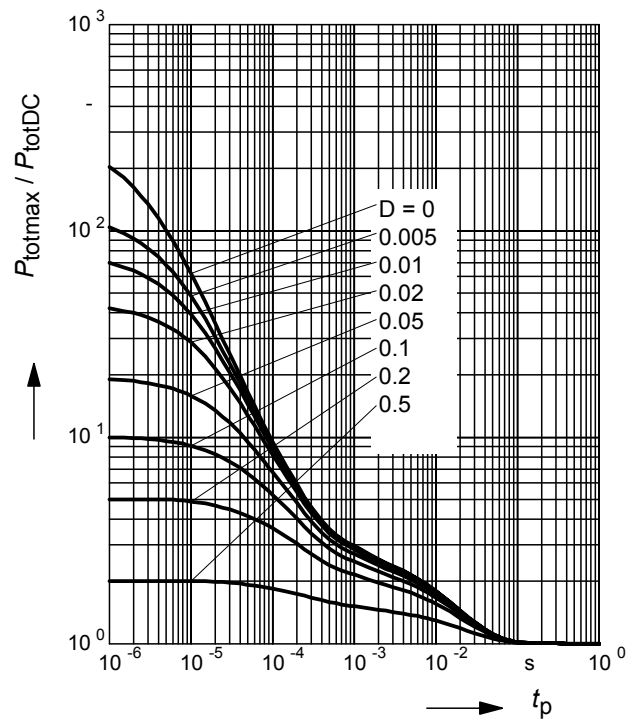
BCR183W



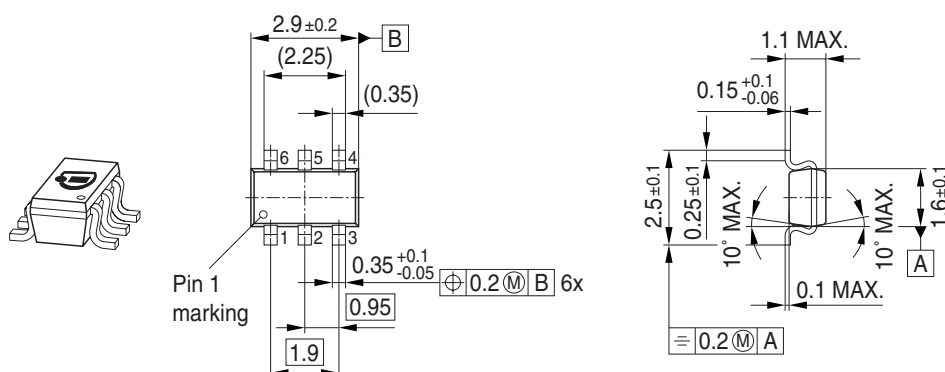
### Permissible Pulse Load

$$P_{totmax}/P_{totDC} = f(t_p)$$

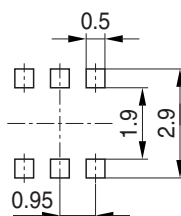
BCR183W



## Package Outline

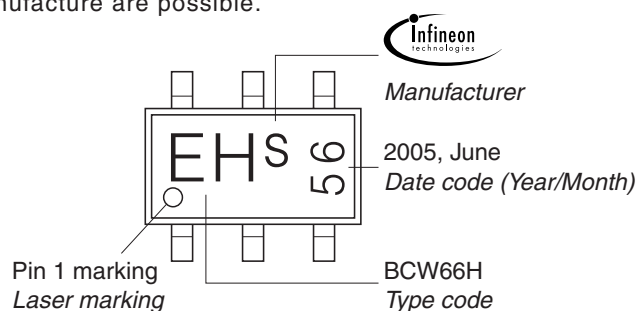


## Foot Print



## Marking Layout (Example)

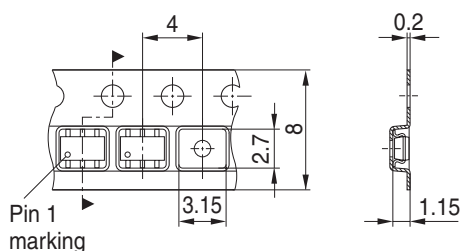
Small variations in positioning of Date code, Type code and Manufacture are possible.



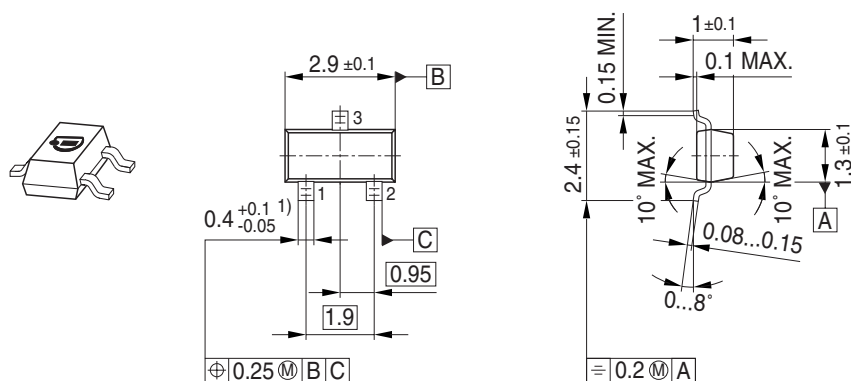
## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

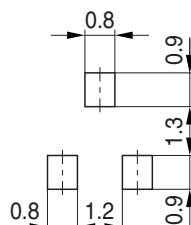


## Package Outline

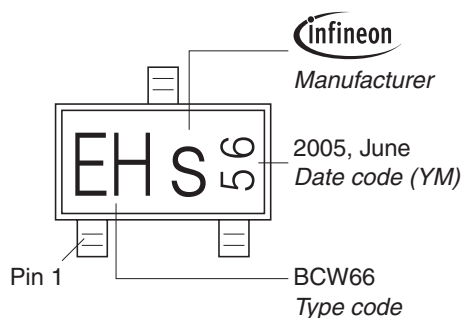


1) Lead width can be 0.6 max. in dambar area

## Foot Print

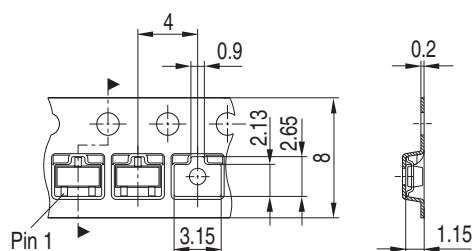


## Marking Layout (Example)



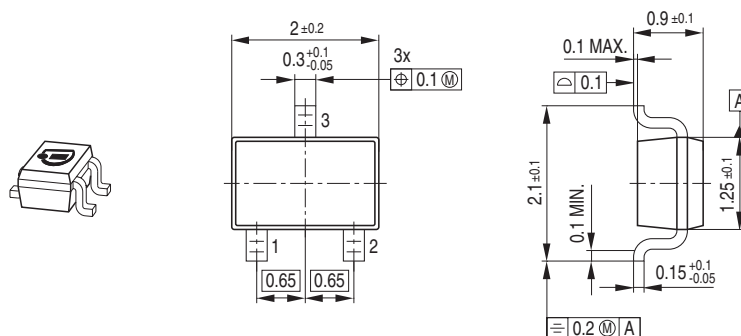
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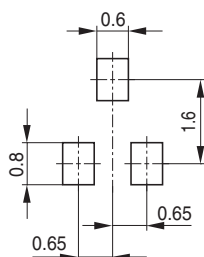




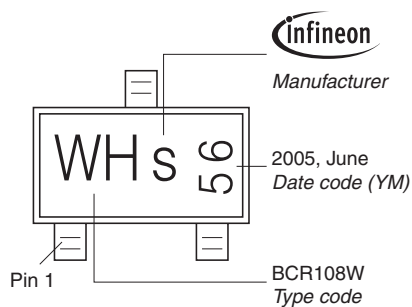
## Package Outline



## Foot Print

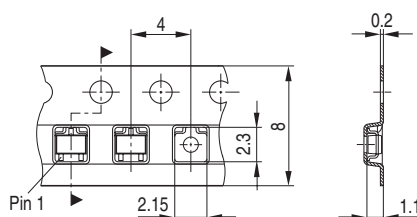


## Marking Layout (Example)

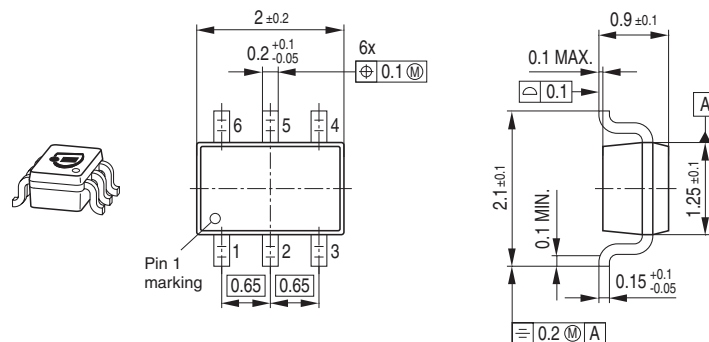


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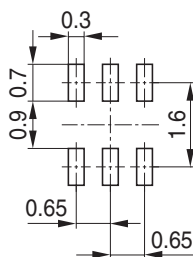
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 Reel  $\varnothing 330$  mm = 10.000 Pieces/Reel



## Package Outline

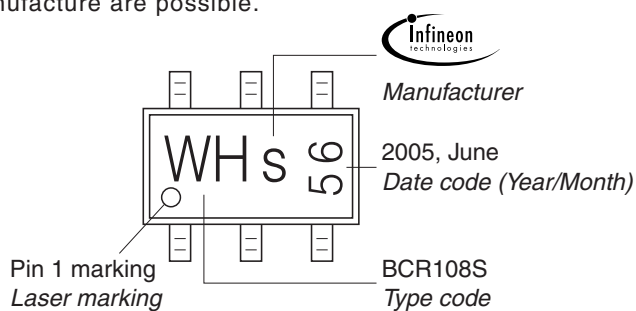


## Foot Print



## Marking Layout (Example)

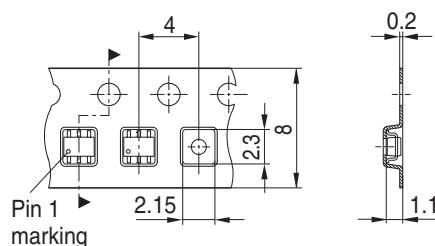
Small variations in positioning of Date code, Type code and Manufacture are possible.



## Standard Packing

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